

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	TDK U.S.A. CORPORATION	10/19/2021
RECEIVING PARTY DATA		
Name:	TDK CORPORATION	
Street Address:	2-5-1, NIHONBASHI, CHUO-KU	
City:	TOKYO	
State/Country:	JAPAN	
Postal Code:	103-6128	
PROPERTY NUMBERS Total: 5		
Property Type	Number	
Application Number:	17086730	
Application Number:	17114881	
Application Number:	17221452	
Application Number:	17367818	
Application Number:	63216476	
CORRESPONDENCE DATA		
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NAME OF SUBMITTER:	JANICE LOGAN	
SIGNATURE:	/Janice Logan/	
DATE SIGNED:	10/29/2021	
Total Attachments: 1		
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ASSIGNMENT

WHEREAS TDK U.S.A. Corporation (herein after "Assignor"), whose post office address is 455 RXR Plaza, Uniondale, New York 11556 (hereinafter referred to as "Assignor"), owns inventions entitled:

Interconnects for Electrical Components Positioned Adjacent to Vehicle Tires (Attorney Docket No. 124151-5002),
Devices and Methods for Determining Impedance of Single Biological Cells (Attorney Docket No. 124151-5003),
Energy Harvesters and Sensors Based on Strain in Mechanical Structures (Attorney Docket No. 124151-5004),
Devices with Multiple Electric Converters for Synchronized Electrical Charge Extraction (Attorney Docket No. 124151-5006), and
Power Distribution System Mountable on a Vehicle Wheel (Attorney Docket No. 124151-5007),

for which U.S. Patent Application Nos. 17/086,730, 17/114,881, 17/221,452, 63/216,476, and 17/367,818 were filed on November 2, 2020, December 8, 2020, April 2, 2021, June 29, 2021 and July 6, 2021, respectively; and

WHEREAS TDK Corporation whose post office address is 2-5-1, Nihonbashi, Chuo-ku, Tokyo 103-6128, Japan (hereinafter referred to as "Assignee") is desirous of securing the entire right, title and interest as sole owner from Assignor in and to these inventions, and in and to the applications of United States Letters Patent on these inventions and the Letters Patent to be issued upon these applications;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, Assignor does hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, its entire right, title and interest in and to these inventions and these applications, and all non-provisional applications, divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patent which may hereafter be filed for these inventions; and Assignor hereby authorizes and requests the Director of Patents and Trademarks of the United States, to issue all Letters Patent of these inventions to Assignee, its successors and assigns, as a sole owner in accordance with the terms of this Assignment;

AND, Assignor hereby covenants that it has the full right to convey the interest assigned by this Assignment, and has not executed and will not execute any agreement in conflict with this Assignment;

IN TESTIMONY WHEREOF, Assignor has hereunto set its hands.

TDK U.S.A. Corporation

Representative: Jeffrey G. Williams

Title: President & COO

Signature:



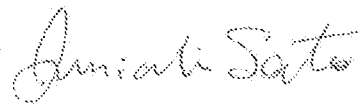
Date: October 19, 2021

TDK Corporation

Representative: Junichi Sato

Title: General Manager of Intellectual Property

Signature:



Date: October 21, 2021

Morgan, Lewis & Bockius LLP